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PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Katsuya SAKAYORI et al.

Group Art Unit: 2823

Application No.: 10/074,224

Examiner: W. David Coleman

Filed: February 14, 2002

Docket No.: 123799

For: WET ETCHED INSULATING MATERIAL AND ELECTRONIC CIRCUIT
COMPONENTS

REQUEST FOR RECONSIDERATION

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In reply to the December 2, 2004 Office Action, reconsideration of the rejections is respectfully requested in light of the following remarks.

Claims 1-104 are pending in this application, claims 1-56 having been withdrawn from consideration.

Rejection Under 35 U.S.C. §102

The Office Action rejects claims 57-78, 80 and 82 under 35 U.S.C. §102(b) over JP 2000-183523 to Takashi et al. ("Takashi"). Applicants respectfully traverse the rejection.

Claim 57 recites: "[a] process for producing an electronic component, comprising the steps of: wet etching a laminate of conductive inorganic material layer-insulating layer-conductive inorganic material layer or a laminate of conductive inorganic material layer-insulating layer to pattern the conductive inorganic material layer; and then performing wet etching to pattern the insulating layer, wherein the insulating layer in the laminate is wet